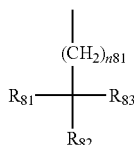
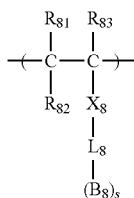


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wherein, in General Formula (II-2), each of R_{81} , R_{82} , and R_{83} independently represents an alkyl group, an alkenyl group, a cycloalkyl group, or an aryl group; $n81$ represents 0 or 1; and at least two of R_{81} to R_{83} may be connected to each other to form a ring, and



wherein, in Formula (V), each of R_{81} , R_{82} , and R_{83} independently represents a hydrogen atom, an alkyl group, a cycloalkyl group, a halogen atom, a cyano group, or an alkoxy carbonyl group; here, R_{82} may be bonded to L_8 to form a ring, and R_{82} in this case represents a single bond or an alkylene group; X_8 represents a single bond or a divalent connecting group; L_8 represents a single bond or an $(s+1)$ valent connecting group, and in the case of being bonded to R_{82} to form a ring, represents an $(s+2)$ valent connecting group; s represents an integer of 1 to 5; here, in a case where L_8 is a single bond, s is 1; and B_8 represents a group containing a cross-linking group.

46. The active light-sensitive or radiation-sensitive resin composition according to claim **45**,

wherein a cross-linking group included in B_8 in General Formula (V) is a hydroxymethyl group, an alkoxyethyl group, an oxirane ring, or an oxetane ring.

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47. The active light-sensitive or radiation-sensitive resin composition according to claim **45**,

wherein B_8 in General Formula (V) is a group which has a phenol structure, a urea structure, or a melamine structure, having a hydroxymethyl group or an alkoxyethyl group.

48. The active light-sensitive or radiation-sensitive resin composition according to claim **47**,

wherein B_8 in General Formula (V) is a group which has a phenol structure having a hydroxymethyl group or an alkoxyethyl group, provided that the hydroxymethyl group is not directly bonded to a nitrogen atom, and the alkoxyethyl group is not directly bonded to a nitrogen atom.

49. The active light-sensitive or radiation-sensitive resin composition according to claim **45**,

wherein the content of the repeating unit represented by General Formula (V) is 1 mol % to 20 mol % with respect to the entirety of repeating units in the resin (A).

50. The active light-sensitive or radiation-sensitive resin composition according to claim **45**,

wherein the bond between X_4 and L_4 in General Formula (I) is a single bond.

51. The active light-sensitive or radiation-sensitive resin composition according to claim **45**,

wherein the content of the repeating unit represented by General Formula (I) is 10 mol % to 40 mol % with respect to the entirety of repeating units in the resin (A).

52. The active light-sensitive or radiation-sensitive resin composition according to claim **45**,

wherein the active light-sensitive or radiation-sensitive resin composition further includes a compound (B) that generates an acid by active light or radiation.

53. The active light-sensitive or radiation-sensitive resin composition according to claim **52**,

wherein the compound (B) that generates an acid by active light or radiation is a compound that generates an acid having a volume of 240 Angstroms³ or greater.

54. A resist film which is formed using the active light-sensitive or radiation-sensitive resin composition according to claim **45**.

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